Notice of Allowability	Application No.	Applicant(s)	
	09/388,031	AKRAM, SALMAN	
	Examiner	Art Unit	
	Eugene Lee	2815	
The MAILING DATE of this communication appear All claims being allowable, PROSECUTION ON THE MERITS IS (herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGOT THE Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this or other appropriate communica GHTS. This application is subje	application. If not included tion will be mailed in due course. THIS	⁄e
1. This communication is responsive to <u>9/9/05</u> .			
2. X The allowed claim(s) is/are 1-4,7,9-28,100-104,107 and 10	<u>9-129</u> .		
 Acknowledgment is made of a claim for foreign priority un a) All b) Some* c) None of the: 1. Certified copies of the priority documents have 2. Certified copies of the priority documents have 3. Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received:	been received. been received in Application No cuments have been received in t	 nis national stage application from the	
Applicant has THREE MONTHS FROM THE "MAILING DATE" of noted below. Failure to timely comply will result in ABANDONM THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.		pry complying with the requirements	
4. A SUBSTITUTE OATH OR DECLARATION must be submi INFORMAL PATENT APPLICATION (PTO-152) which give	itted. Note the attached EXAMINes reason(s) why the oath or dec	ER'S AMENDMENT or NOTICE OF aration is deficient.	
 5. CORRECTED DRAWINGS (as "replacement sheets") muss (a) including changes required by the Notice of Draftspers 1) hereto or 2) to Paper No./Mail Date (b) including changes required by the attached Examiner's Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR 1. each sheet. Replacement sheet(s) should be labeled as such in the deposit of the deposit	on's Patent Drawing Review (P's Amendment / Comment or in the drawing should be written on the drawe header according to 37 CFR 1.1	e Office action of awings in the front (not the back) of 21(d). L must be submitted. Note the	d .
AM-21-2-4/2)			
Attachment(s) 1. Notice of References Cited (PTO-892)	5. Notice of Inform	al Patent Application (PTO-152)	
2. Notice of Draftperson's Patent Drawing Review (PTO-948)	6. ☐ Interview Summ Paper No./Mail		
3. Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date		ndment/Comment	
4. Examiner's Comment Regarding Requirement for Deposit of Biological Material Output Date	9. Other	ement of Reasons for Allowance	
	EUGAN	6-LCC	
		1411 3 C I C	

Application/Control Number: 09/388,031

Art Unit: 2815

DETAILED ACTION

Allowable Subject Matter

- 1. Claims 1-4, 7, 9-28, 100-104, 107, and 109-129 are allowed.
- 2. The following is an examiner's statement of reasons for allowance: The references of record, either singularly or in combination, do not teach or suggest at least "a metallization structure comprising a conductive line for transmitting a signal laterally across the substrate, the conductive line consisting essentially of: a metal layer; a single conducting layer overlying and substantially coextensive with the metal layer, the single conducting layer defining an upper surface of the conductive line, the single conducting layer selected from the group consisting of aluminum and copper; and metal spacers extending at least substantially to a height of the sidewalls of the single conducting layer and metal layer" (claims 1-4, 7, 9-15, and 100). Hata 0502647 A2 EPO does not disclose the titanium nitride cap (single conducting layer) selected from the group consisting of aluminum and copper. It would not have been obvious to make the titanium nitride cap either aluminum or copper since the metal line 18 underneath is already aluminum. Further, the cited prior art does not disclose the single conducting layer defining an upper surface of the conductive line, rather, the cited prior art discloses metal layers enclosing the single conducting layer so that the single conducting layer does not define an upper surface of the conductive line.

Regarding claims 102-104, 107, and 109-115, the references of record, either singularly or in combination, do not teach or suggest at least "a structure for transmitting a signal across a semiconductor device, the structure comprising a conductive line, the conductive line consisting essentially of a metal layer; a single conducting layer overlying and substantially coextensive

Page 2

Art Unit: 2815

with the metal layer, the single conducting layer defines an upper surface of the conductive line, the single conducting layer selected from the group consisting of aluminum and copper; and metal spacers extending at least substantially to a height of the sidewalls of the single conducting layer and metal layer."

Regarding claims 16-25, and 101, the references of record, either singularly or in combination, do not teach or suggest at least "a metallization structure, comprising a substrate having a metal layer extending over the substrate, the metal layer at least underlying a conductive line; a conductive layer of the conductive line in contact with the metal layer and the metal spacer, the metal spacer and the conductive layer substantially filling the aperture, the conductive layer having an upper surface substantially coincident with an upper surface of the dielectric layer."

Regarding claims 26-28, the references of record, either singularly or in combination, do not teach or suggest at least "a metallization structure, comprising a substrate having a metal layer extending over the substrate, the metal layer at least underlying a conductive line; a conductive layer of the conductive line in contact with the metal layer and the metal spacer, the metal spacer and the conductive layer nearly filling the aperture, at least one upper metal layer on the conductive layer, the at least one upper metal layer having an upper surface substantially coincident with an upper surface of the dielectric layer and an uppermost extent of the metal spacer."

Regarding claims 116-125, and 129, the references of record, either singularly or in combination, do not teach or suggest at least "a structure for transmitting a signal laterally across a substrate, the structure comprising: a substrate having a metal layer of a conductive line; a

conductive layer of the conductive line in contact with the metal layer and the metal spacer, the conductive layer having an upper surface substantially coincident with an upper surface of the dielectric layer."

Regarding claims 126-128, the references of record, either singularly or in combination, do not teach or suggest at least "a structure for transmitting a signal laterally across a substrate of a semiconductor device, the structure comprising: a substrate having a metal layer of a conductive line disposed thereon; a conductive layer of the conductive line in contact with the metal layer and the metal spacer, the metal spacer and the conductive layer nearly filling the aperture; and at least one upper metal layer on the conductive layer having an upper surface substantially coincident with an upper surface of the dielectric layer and an uppermost extent of the metal spacer."

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

INFORMATION ON HOW TO CONTACT THE USPTO

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Eugene Lee whose telephone number is 571-272-1733. The examiner can normally be reached on M-F 8-5.

Application/Control Number: 09/388,031

Art Unit: 2815

Page 5

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on 571-272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Eugene Lee

November 18, 2005

AU2815